



Semiconductor Device Type: HPA 006 VDFN 7x5x0.9mm NiPdAu			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)			J-STD-609A Product Marking and/or Pkg. Labeling e4
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	(mg) Total	Mold Compound	% of Total Weight	
Silica, fused	60676-86-0	Mold Compound	50.643	41.679	506.430	46.31	Mold Compound		56.27
Epoxy Resin	Trade Secret	Mold Compound	2.729	2.246	27.291				
Phenolic Resin	Trade Secret	Mold Compound	2.729	2.246	27.291				
Carbon Black	1333-86-4	Mold Compound	0.169	0.139	1.688				
Copper	7440-50-8	Lead Frame	39.445	32.464	394.454				
Iron	7439-89-6	Lead Frame	0.932	0.767	9.324	33.36	Lead Frame		40.54
Zinc (Metal)	7440-66-0	Lead Frame	0.101	0.083	1.014				
Phosphorous	7723-14-0	Lead Frame	0.061	0.050	608				
Silver	7440-22-4	Die Attach	0.225	0.185	2.250				
Methacrylic acid, isobornyl ester	7534-94-3	Die Attach	0.042	0.035	420				
1,3-Bismaleimidobenzene polymer with oxirane mono-2-propenoate	3006-93-7 1017237-78-3	Die Attach	0.023 0.011	0.019 0.009	225 105	0.25	Die Attach		0.30
Silicon	7440-21-3	Chip (Die)	1.460	1.202	14.600				
Gold	7440-57-5	Wire Bond	0.250	0.206	2.500				
Nickel	7440-02-0	Plating on external leads (pins)	1.112	0.915	11.118				
Palladium	7440-05-3	Plating on external leads (pins)	0.043	0.035	426				
Gold	7440-57-5	Plating on external leads (pins)	0.026	0.021	256	1.20	Chip (Die)		1.46
<b>TOTALS:</b>			<b>100.000</b>	<b>82.300</b>	<b>1,000,000</b>				
<b>0.0823 g Total Mass</b>									
This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero)									
Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.									
If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.									
Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at <a href="http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/">http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/</a>									
The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.									
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Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at <a href="http://echa.europa.eu/web/guest/candidate-list-table">http://echa.europa.eu/web/guest/candidate-list-table</a>									
						0.21	Wire Bond		0.25
						0.97	Plating on external leads (pins)		1.18
						1.20	Total (mg)		1.46
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